

AMENDMENTS TO THE CLAIMS

Please amend claims 7-8, 11-12, 19, 23 and 25-27 and cancel claim 24 as follows.

1. (previously presented) A method of forming an interconnector component for an electrochemical converter, comprising the steps of:
 - casting a first slurry into a layer to form a first tape;
 - casting a second slurry into a layer to form a second tape;
 - laminating the first tape to the second tape to form a laminated structure; and
 - hot pressing the laminated structure using a combination of heat and pressure to form the interconnector component.
2. (original) The method of claim 1, wherein the first slurry comprises a powder comprising chromium.
3. (original) The method of claim 2, wherein the powder comprises at least 95% chromium.
4. (original) The method of claim 1, wherein the second slurry comprises a powder comprising lanthanum chromite.
5. (original) The method of claim 1, further comprising the step of trimming one of said first tape and said second tape.
6. (original) The method of claim 1, further comprising the step of trimming the laminated structure.
7. (currently amended) The method of claim 1, further comprising the step of trimming ~~the sintered structure~~ interconnector component.
8. (currently amended) The method of claim 1, further comprising the step of coating the ~~sintered structure~~ interconnector component with a compound.

9. (previously presented) An interconnector component for an electrochemical converter comprising:

a first layer comprising a material having a composition that is at least 95% chromium;
and

a second layer comprising lanthanum chromite laminated to the first layer, wherein the first layer and the second layer are hot pressed using a combination of heat and pressure to form the component.

10. (original) The component of claim 9, wherein the component has a thickness of between about 0.01 and about 0.03 inches.

11. (currently amended) The component of claim 9, wherein one of the first and second layer forms a flat surface for opposing a textured surface of an adjacent electrolyte plate forming a flow passage in a stacked assembly that includes the interconnector ~~plate~~component.

12. (currently amended) The component of claim 9, wherein one of the first and second layer forms a textured surface for opposing a flat surface of an adjacent electrolyte plate forming a flow passages in a stacked assembly that includes the interconnector ~~plate~~component.

13. (previously presented) A method of forming a high density interconnector component for an electrochemical converter, comprising the steps of:

casting a slurry material into a sheet; and

applying heat and pressure to sinter the sheet to form the interconnector component.

14. (original) The method of claim 13, wherein the step of applying heat and pressure forms a sintered structure having a specific density of at least 96%.

15. (original) The method of claim 13, further comprising the step of providing the material as raw material in a powder form.

16. (original) The method of claim 13, further comprising the step of laminating the green sheet prior to the step of applying heat and pressure.

17. (original) The method of claim 13, further comprising the step of sintering the green sheet prior to the step of applying heat and pressure.

18. (original) The method of claim 13, wherein the material comprises one of: silicon carbide SiC, high chromium alloys, chromium iron alloys (Cr-5wt%Fe-1wt% Y_2O_3), chromium magnesium alloys (Cr-5wt%Ni-1wt%MgO) and mixtures thereof.

19. (currently amended) The method of claim 13, further comprising the step of coating the sintered structure interconnector component with a compound.

20. (original) The method of claim 19, wherein the step of coating comprises using plasma spray, chemical vapor deposition, or physical vapor deposition techniques.

21. (canceled)

22. (previously presented) The method of claim 13, wherein the component has a thickness of between about 0.01 and about 0.03 inches.

23. (currently amended) An interconnector plate for an electrochemical converter formed by the method of claim 13, wherein material forming the interconnector plate has a composition that is at least 95% chromium.

24. (canceled)

25. (currently amended) An interconnector plate for an electrochemical converter formed by the method of claim ~~13~~23, wherein the interconnector plate has flat surfaces which oppose textured surfaces of adjacent electrolyte plates forming flow passages in a stacked assembly that includes the interconnector plate.

26. (currently amended) An interconnector plate for an electrochemical converter formed by the method of claim ~~13~~23, wherein the interconnector plate has textured surfaces which

oppose flat surfaces of adjacent electrolyte plates forming flow passages in a stacked assembly that includes the interconnector plate.

27. (currently amended) A method of forming a high density thin interconnector plate for an electrochemical converter, comprising the steps of:

casting a slurry material into a sheet; and

applying heat and pressure to sinter the sheet to a thickness of less than about 0.03 inches to form ~~the~~a thin interconnector component.